

AK 2815



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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

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In re the Application of:  
Baldonado, et al. **FEB 25 2004**  
Serial No.: 10/066,421 Conf. No.: 5110  
Filed: 01/30/2002 Docket No.: TI-32857  
For: Method and System of Wire Bonding Using Interposer Pads Examiner: Clark, Sheila Art Unit: 2815

**Supplemental Appeal Brief**

Director of the United States  
Patent and Trademark Office  
P.O. Box 1450  
Alexandria, VA 22313-1450

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Jay M. Cantor

Dear Sir:

Supplemental to the Brief on Appeal and responsive to the Office action dated November 18, 2003, the following additional arguments are provided.

It is initially noted that all newly raised objections and rejections, even if proper, which all but one are not as will be demonstrated, are based on matters which have existed ab initio in this application except for the drawing amendment, which is also proper.

In response to the objection to the amended drawings, it should be noted that the amendments thereto involve the addition of solder balls in a ball grid array in figures 1 to 4 which are unnumbered and standard in the art. These elements are not new matter and are specifically recited in the specification as originally filed at page 5, line 12. The ball

grid array was also set forth in original claim 7. Accordingly, the addition of these well known and recited elements to the drawings does not involve new matter.

With reference to claim 7, the objection is to an original claim which was not previously rejected for the reason now advanced. Accordingly, the rejection at this time and in the manner rejected is improper. However, appellants will agree to cancel the reference to the trademark from claim 7 and any other claim in which this trademark appears (claim 14) upon completion of this appeal.

With reference to the rejection of claims 1, 2 and 4 to 21 under 35 U.S.C. 112, first paragraph, all of the attachments shown in figures 1 to 4 which are to a ball (12, 23) are to balls and are therefore ball bonds, whereas all of the attachments in these figures to a stitch 14 are stitch bonds as is well known in the art for decades.

The rejection applied to claim 22 in the third paragraph on page 3 of the last Office action is not understood since claim 22 was canceled.

The interposer can take any form and is shown in figures 2 and 4 as a pad 21. The term "electroless" is a system for chemical plating without the use of electricity. A definition is attached hereto. Electroless plating has been known for many decades if not a century.

With reference to the objection raised at page 5, paragraphs 3 and 4, the "ball grid array", which is specifically mentioned in the specification, is a well known term in the art which should need no further explanation to a person with even minimal skill in the art. It is not believed that appellants should be required to provide a definition for every standard term of the art used herein which should be well known even to a novice in the art.

The objection to claim 3 on page 4, paragraph 4, is not understood since this claim has been canceled.

A plurality of interposer pads are shown in figure 6.

With reference to the objection to the drawings in the last paragraph on page 4, it is respectfully submitted that an "electroless" substrate cannot be drawn as such, especially considering the definition of this term. The "ball grid array" is shown in the drawings objected to. The plurality of interposer pads is shown in figure 6. The term "electrically floats" has nothing to do with flying through the air, but rather means that the interposer pad is not connected to a voltage source. This cannot be shown other than the manner in which it has been shown.

With reference to the rejection of claims 1, 2, 4 and 6 to 21 under 35 U.S.C. 102(a) as being anticipated by Schmidt et al. (U.S. 6,232,561), appellants rely on the argument presented in the Brief on Appeal.

The objection to claim 5 is not understood since this claim depends from claim 1.

In view of the above remarks as well as the remarks presented in the Brief on Appeal, reversal of the final rejection and allowance of the appealed claims is urged that justice be done in the premises.

Respectfully submitted,



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**Definition:**

The deposition of a metallic coating, usually nickel, on a component by chemical means rather than by electroplating; the component is immersed in a solution containing a reducing agent.

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